In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Claims 1-21 (Withdrawn)

- 22. (Currently Amended) A polycide gate structure, comprising:
 - (1) a polysilicon structure formed upon said a substrate and having laterals;
- (2) an insulating structure disposed on said laterals of said polysilicon structure for insulating said polysilicon structure;
 - (3) a silicide structure formed upon said polysilicon structure and having laterals; and
- (4) a protecting structure disposed formed by means of chemical vapor deposition (CVD) on said laterals of said silicide structure of for protecting said silicide structure.
- 23. (Currently Amended) The structure as claimed in claim 22, wherein said insulating layer structure is silicon dioxide (SiO2).
- 24. (Currently Amended) The structure as claimed in claim 22, wherein said silicide layer structure upon said polysilicon layer structure comprises a barrier, a tungsten layer and a silicon nitride (SiNX) layer in sequence.
- 25. (Original) The structure as claimed in claim 24, wherein said barrier is titanium nitride (TiN).
- 26. (Cancelled)
- 27. (Currently Amended) The structure as claimed in claim 22, wherein said protecting layer structure has a thickness ranged from 50 to 500 A.
- 28. (Currently Amended) The structure as claimed in claim 22, wherein said protecting layer structure is silicon nitride (SiNX).

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- 29. (Currently Amended) The structure method as claimed in claim 22, wherein said polysilicide polysilicon structure is defined via an anisotropic dry etcher.
- 30. (Original) The structure as claimed in claim 22, wherein said insulating structure is formed by means of a dry oxidation method.
- 31. (Currently Amended) The structure as claimed in claim 22, wherein said polyeide structure is defined via anisotropic dry etcher.
- 32. (Original) The structure as claimed in claim 22, wherein said protecting structure is defined via an anisotropic dry etcher.

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